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8071-112T (OPP031222US)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

APPLICANT: Hong-Sick PARK et al. EXAMINER: Long Pham  
SERIAL NO.: 10/772,293 GROUP ART UNIT: 2814  
FILED: February 6, 2004  
FOR: ETCHANT FOR SIGNAL WIRE AND METHOD OF  
MANUFACTURING THIN FILM TRANSISTOR ARRAY PANEL  
USING ETCHANT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE TO RESTRICTION REQUIREMENT**

Sir:

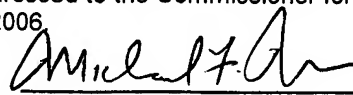
This paper is submitted in response to the August 10, 2006 Office Action issued by the United States Patent and Trademark Office in connection with the above-identified application. A response to the August 10, 2006 Office Action is due on September 10, 2006. Therefore, this paper is being timely filed.

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**CERTIFICATE OF MAILING 37 C.F.R. § 1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail, postpaid in an envelope, addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on August 28, 2006.

Dated: August 28, 2006

  
Michael F. Morano